

ABSTRACT OF THE DISCLOSURE

There is provided a method for fabricating electrical wirings capable of being manufactured with low cost and easily applied to large-scale substrates. A
5 photosensitive ground resin film is formed on an insulating substrate by coating process. The ground resin film is subjected to exposure and development processes, by which a ground resin film patterned into a wiring pattern is obtained. Then, on the patterned ground resin film, a low-
10 resistance metal film made of Cu is formed by electroless plating.

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